

ULTRA LOW POWER EMBEDDED COMPUTER

Gx101

PENTIUM CLASS EMBEDDED COMPUTER - 200/300 MHz

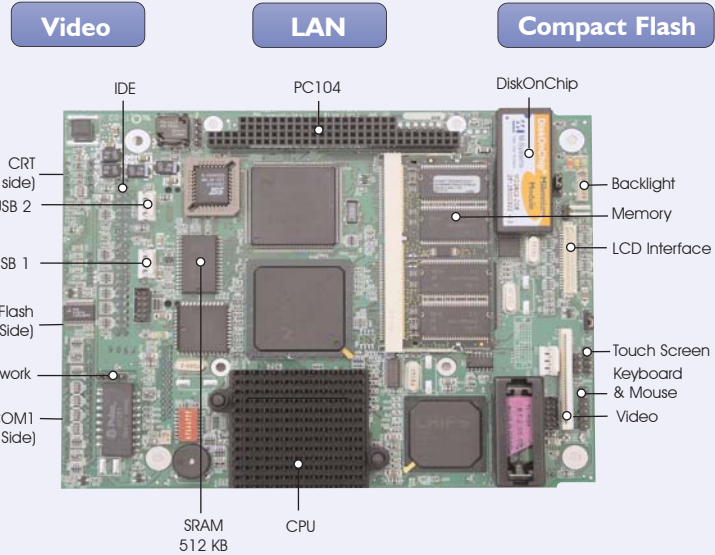
The Shortest path from ideas...to product.

Features

- Ultra low power, fanless operation up to 300 MHz
- Over 250,000 hours MTBF
- 5 year product availability guarantee
- 32 to 128 MB SODIMM SDRAM
- CRT/LCD interface up to 4 MB display memory
- Compact flash socket up to 512 MB
- 10/100Base-T Ethernet interface
- 3 serial ports, dual USB, 512 Bytes EEPROM, 64-bit unique electronic ID
- Touch screen interface

Applications

- Robotic
- Medical
- Test & Measurement
- Transportation
- Avionics
- Mil/Aerospace
- e-Kiosks
- Industrial Automation
- Inventory Management
- Point Of Sale Terminal



Technical Data

System

CPU	Embedded NS Geode GX1 200 to 300 MHz low power processor (fanless)
SYSTEM MEMORY	32 to 128 MB system RAM
CHIPSET	NS CS5530
BIOS	GS customized embedded BIOS on 256 KB flash memory
SSD	Supports CompactFlash™ card and DiskOnChip
BUS	PCI (33 MHz) / ISA (8.33 MHz)
POWER CONSUMPTION	Typical: 5.0 V @ 1.2 A [200 MHz CPU]
SIZE	5.25" x 6.85"
TEMPERATURE	-40°C ~ 85°C operating
OPERATING HUMIDITY	0% ~ 90% relative humidity, non-condensing

I/O

STANDARD I/O	EIDE (Ultra DMA33), 1 x K/B, 1 x Mouse, 1 x RS-232, 2 x RS-485, 1 x LPT, 2 USB ports (USB 1.0 compliant)
NETWORK	10/100BASE-T (AMD 79C973 chipset)

Display

CHIPSET	B69000
MEMORY SIZE	2Mbytes
RESOLUTION	Supports up to 1024x768 @ 16 bpp (60 Hz)
LCD INTERFACE	18-bit TFT panels up to SVGA resolution

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Features Description

CPU	<p>Embedded low power NS GX1 200 to 300 MHz processor L1 Cache - 16 KB write-back data Five-stage pipelined integer unit Integrated Floating Point Unit (FPU) Memory Management Unit (MMU) Supports Intel's MMX instruction set extension for multimedia acceleration Core voltage - 1.8V - 2.2V Passive heatsink</p>
Chipset	NS Geode GX1 CS5530A embedded chipset
System BUS	<p>66/100 MHz system bus frequency PCI: 33 MHz (supports up to three PCI bus masters) ISA: 8 MHz</p>
BIOS	System and video BIOS with TME extensions in 256 KB flash device programmable on-board
Memory	One 144-pin SODIMM socket support 3.3V SDRAM 32 to 128 MB (PC-100 and PC-133)
Flash / Disk Interface	Compact Flash socket for on-board flash disk up to 512 MB
Video Interface	<p>Chips & Technologies 69000 with 2 MB VRAM built-in CRT mode up to 1280 X 1024 @ 16-bit color resolution LCD mode up to 1024 X 768 @ 24-bit color resolution Supports LCD/TFT/STN/EL 3.3V or 5V displays Supports up to 18-bit LCD on TTL interface</p>
Network Interface	<p>AMD 79C973 chipset IEEE 802.3u 100 BASE-T Fast Ethernet</p>
DiskOnChip Interface	One 32-pin JEDEC DIP socket, accepts M-Systems DiskOnChip
EIDE Interface	<p>Enhanced IDE interface supports up to two IDE devices. PIO Mode 4 transfers at up to 16 MB/sec. Support for Ultra DMA/33 synchronous DMA mode transfers at up to 33 MB/sec</p>
COM1-3 Interface	1 RS-232 port 16C550 compatible and 2 RS-485 ports
LPT Interface	Bi-directional/EPP/ECP compatible
USB Interface	Two USB ports
Other Embedded Features	<p>Electronic ID APM (Advanced Power Management) for Legacy power management Serial EEPROM - supports batteryless boot capability 128 Bytes EEPROM available for OEM use Battery Backed SRAM up to 512 KB ESD 10,000V MTBF 250,000 Hours</p>

Ordering Information

GX101LV-20-1-C	GX101 WITH 200MHZ CPU, 64 MB SDRAM, 4 SERIAL, LAN, USB, TOUCH SCREEN, 512K NVRAM, -0°C TO +65°C OPERATING TEMPERATURE
GX101LV-30-1-C	GX101 WITH 300MHZ CPU, 64 MB SDRAM, 4 SERIAL, LAN, USB, TOUCH SCREEN, 512K NVRAM, -0°C TO +65°C OPERATING TEMPERATURE
GX101LV-20-2-E	GX101 WITH 200MHZ CPU, 128 MB SDRAM, 4 SERIAL, LAN, USB, TOUCH SCREEN, 512K NVRAM, -40°C TO +85°C OPERATING TEMPERATURE
GX101LV-30-2-C	GX101 WITH 300MHZ CPU, 128 MB SDRAM, 4 SERIAL, LAN, USB, TOUCH SCREEN, 512K NVRAM, -0°C TO +65°C OPERATING TEMPERATURE

CONTACT TME FOR OTHER CONFIGURATIONS

